ABSTRACT

A sticking apparatus 10 includes a sticking table 11 supporting a semiconductor wafer W and a sticking unit 12 sticking a heat sensitive adhesive sheet S to the semiconductor wafer W. The sticking unit 12 includes a peeling section that, when paying out a raw sheet L having adhesive sheet S laminated to one side face of a release liner PS, peels off the release liner PS and the adhesive sheet S and a sheet preliminary peeling unit 40 provided at an upstream side of the peeling section in a pay-out direction of the raw sheet. The sheet preliminary peeling unit 40 includes a moving member 50 that moves to and from in a state of being pinched between the release liner PS and the adhesive sheet S. The preliminarily peeled-off release liner PS and adhesive sheet S are temporarily re-bonded by a temporary re-bonding unit 41, enabling to stick the adhesive sheet S on the wafer W.